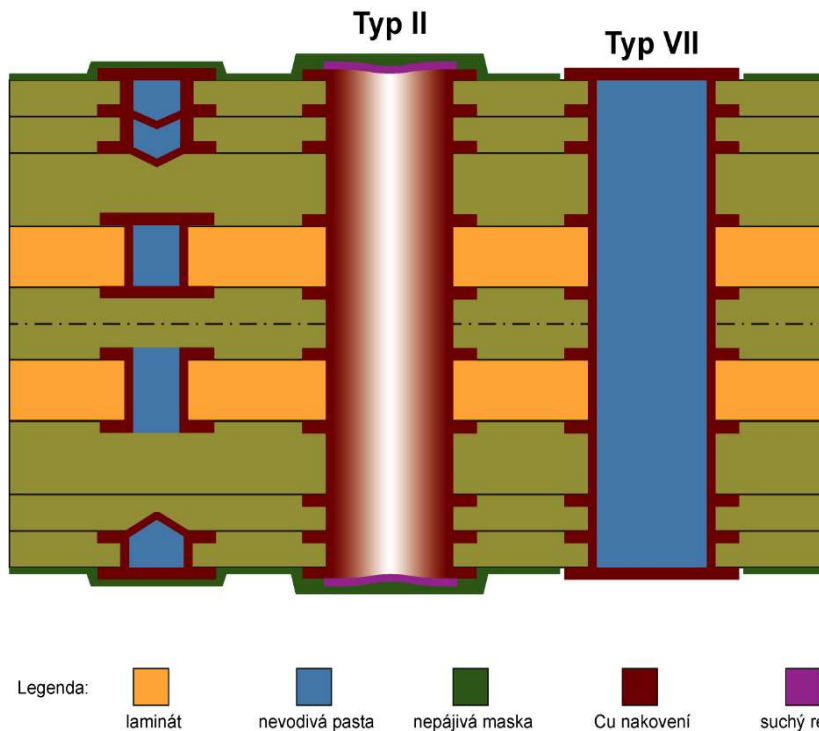


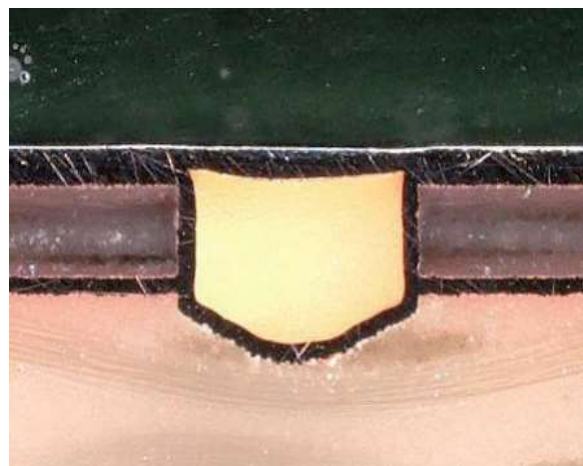
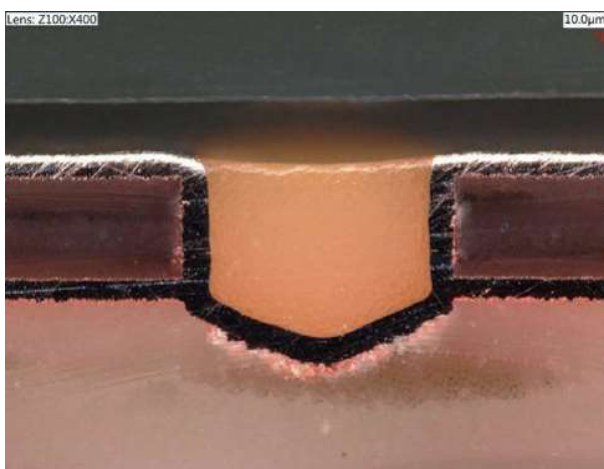
Via filling

Via filling with non-conductive paste

For filling holes, we use technology from the company I.T.C. , which, thanks to two heads, can also fill blind holes. We fill the boards according to IPC 4761 type VII. The holes are plated with copper and the final surface treatment. The technology thus enables via-in-pad.

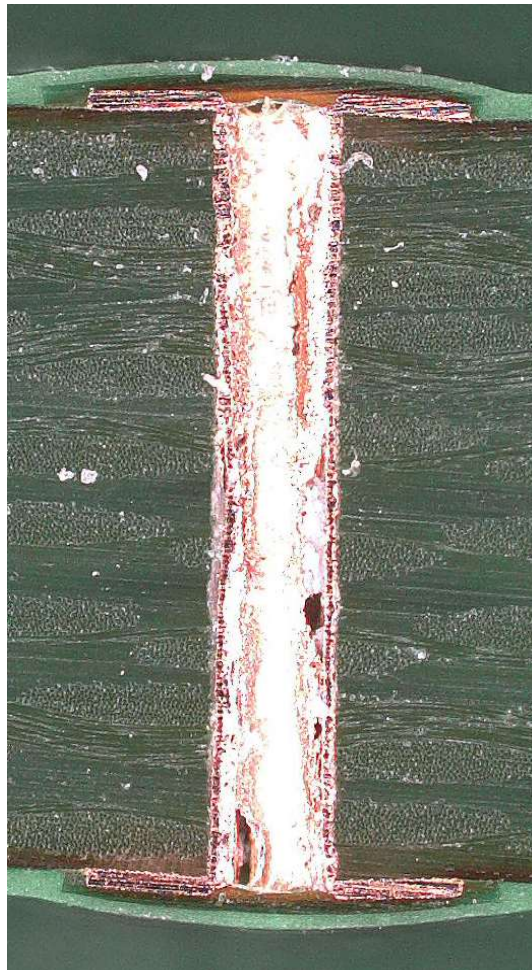


If not stated otherwise, all through holes (VIA) are always filled up to drill diameter of 0.45 mm. It is ideal to specify the diameter of the hole that the customer requires to be filled, or to indicate the maximum diameter of the filled holes. If you want to fill only the selected holes (area), you must specify them in a separate layer, or in the attached drawing.



Cover / overlay with dry resist

The inside of the hole is not filled with non-conductive paste, but is only covered on both sides with dry resist and then covered with a non-soldering mask. The diameter of the drilled hole max. 0.35 mm.



Information about via fill - specification

hole after plating	min. 0,1 mm
hole after plating	max. 2,0 mm
aspect ratio for plated holes	max. 40:1
aspect ratio blind drilling	max. 1:15
according to IPC-4761 we are able to do type	VII
thickness of PCB	0,4-3,2 mm

The hole to be filled must be atleast 5 mm from the edge of the board.

More information about TAIYO paste: <https://www.gatema.cz/file-link/plnici-pasta-tds-thp-100dx1.pdf>

aspectratio plugging from 1:1 to 1:40

